



Material Content Data Sheet



Sales Product Name				IKFW40N60DH3E		Issued		1. August 2018	
MA#				MA002739416					
Package				PG-HSIP247-3-1		Weight*		5787.27 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.563	0.01	0.01	97	97	
chip_2	inorganic material	silicon	7440-21-3	2.028	0.04	0.04	350	350	
leadframe	inorganic material	phosphorus	7723-14-0	0.164	0.00		28		
	non noble metal	iron	7439-89-6	0.545	0.01		94		
	non noble metal	copper	7440-50-8	544.561	9.41	9.42	94097	94219	
	non noble metal	aluminium	7429-90-5	7.578	0.13	0.13	1309	1309	
wire	inorganic material	zinc oxide	1314-13-2	0.214	0.00		37		
encapsulation	plastics	silicone resin	-	0.482	0.01		83		
	inorganic material	alumina	1344-28-1	4.662	0.08		806		
	organic material	carbon black	1333-86-4	21.976	0.38		3797		
	plastics	epoxy resin	-	417.544	7.21		72149		
	inorganic material	silicon dioxide	60676-86-0	1758.080	30.38	38.06	303785	380657	
leadfinish	non noble metal	tin	7440-31-5	16.291	0.28	0.28	2815	2815	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.456	0.01	0.01	79	80	
solder	non noble metal	antimony	7440-36-0	0.204	0.00		35		
	noble metal	silver	7440-22-4	0.510	0.01		88		
	non noble metal	tin	7440-31-5	1.327	0.02	0.03	229	352	
heatspreader	inorganic material	phosphorus	7723-14-0	0.903	0.02		156		
	non noble metal	iron	7439-89-6	3.010	0.05		520		
	non noble metal	copper	7440-50-8	3006.169	51.95	52.02	519445	520121	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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